

Title (en)

METHOD FOR PRODUCING A PROTECTION FOR CHIP EDGES AND SYSTEM FOR THE PROTECTION OF CHIP EDGES

Title (de)

VERFAHREN ZUM HERSTELLEN EINES SCHUTZES FÜR CHIPKANTEN UND ANORDNUNG ZUM SCHUTZ VON CHIPKANTEN

Title (fr)

PROCEDE D'OBTENTION D'UNE PROTECTION DES BORDS D'UNE PUCE, ET DISPOSITIF DE PROTECTION Y RELATIF

Publication

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Application

EP 03702311 A 20030107

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Abstract (en)

[origin: WO03058704A1] The invention relates to a method for producing a protection for the chip edges of electronic components that are not provided with a housing, according to which semiconductor chips provided with a laterally open bonding channel are mounted on a substrate with a tape interposed between. The invention further relates to a system for protecting chip edges. The aim of the invention is to provide a method which is easy to carry out and to provide a system for the secure protection of chip edges/corners. This aim is achieved by using for the assembly of the semiconductor chip on the substrate a tape whose cross-section is smaller than the cross-section of the semiconductor so that between the semiconductor and the substrate, along its outer edge, a peripheral recessed section is formed as a capillary. After establishment of the electrical connections between the semiconductor and the substrate, in a first step, a flowable encapsulation material is introduced into the bonding channel by wire-bonding until the encapsulation material evenly encloses the borders of the semiconductor chip. In a second step, the bonding channel is completely filled with the encapsulation material.

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IPC 8 full level

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